

FIG.1

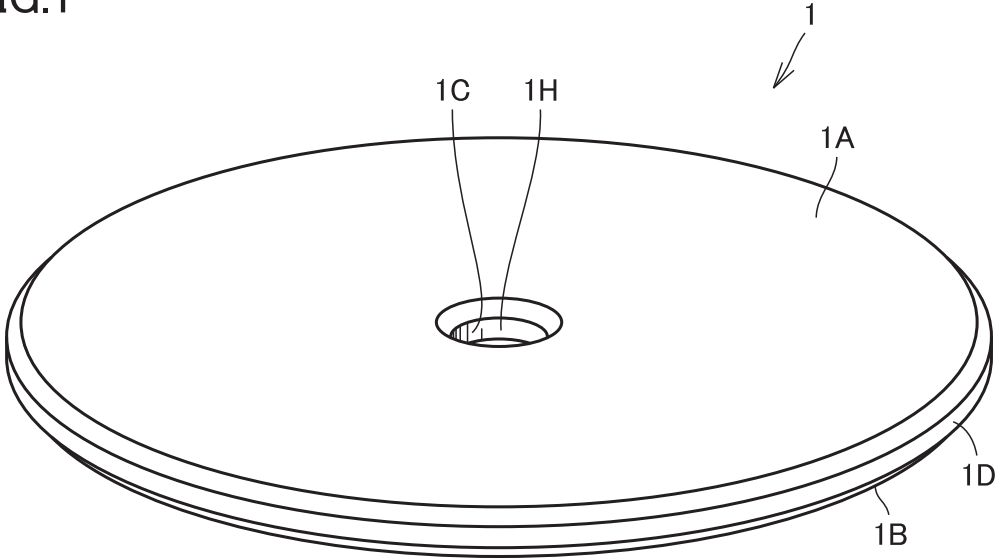


FIG.2

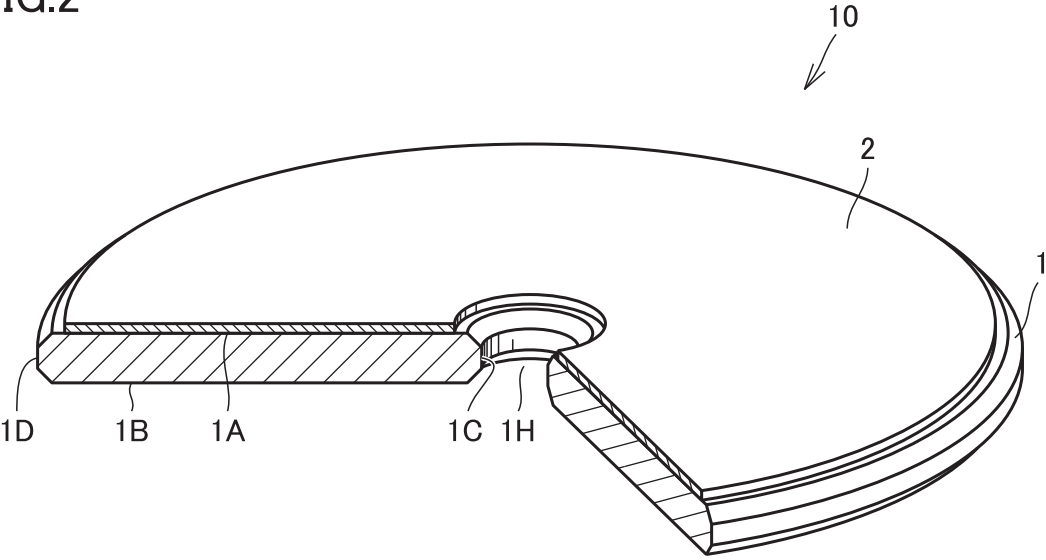


FIG.3

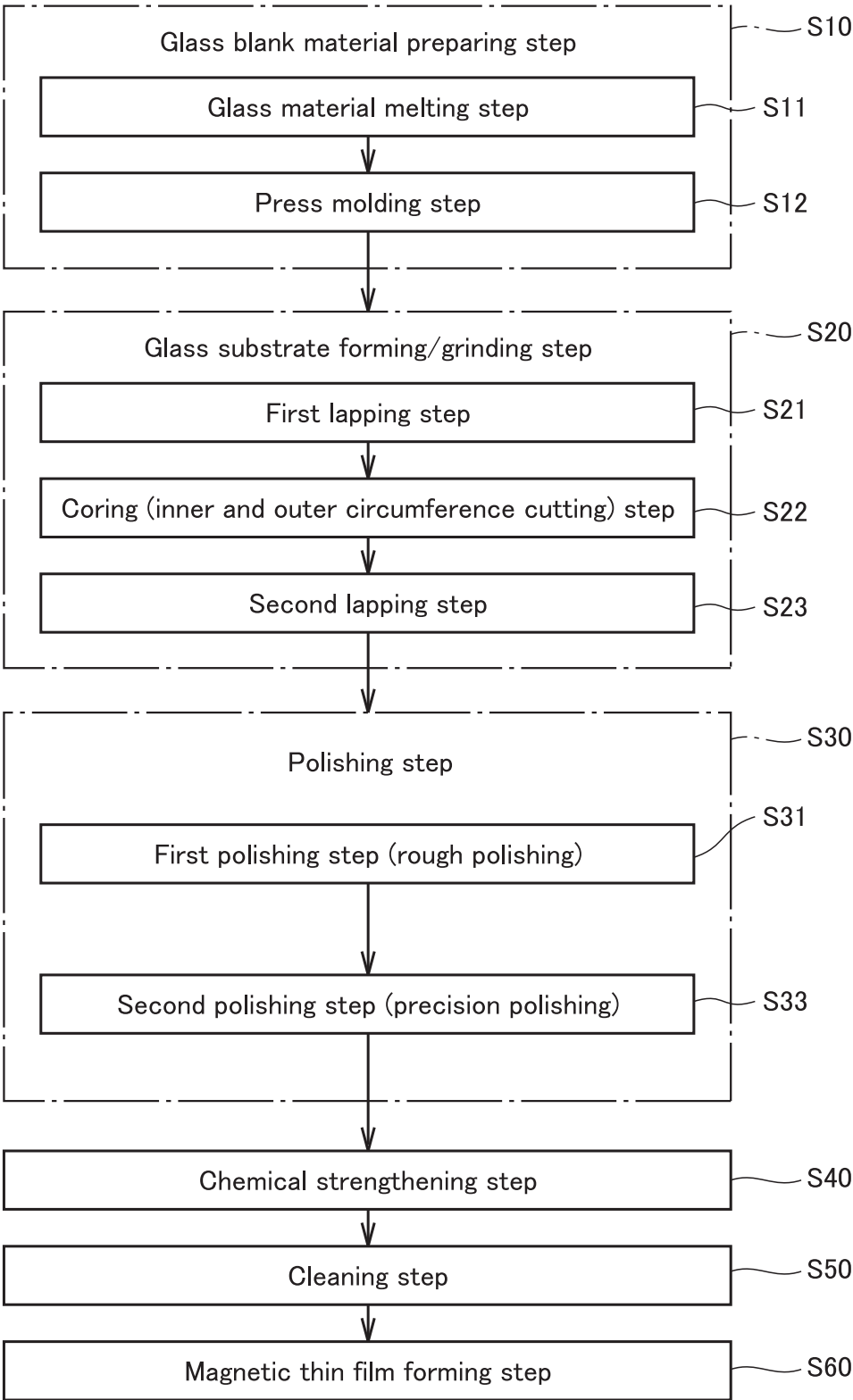


FIG.4

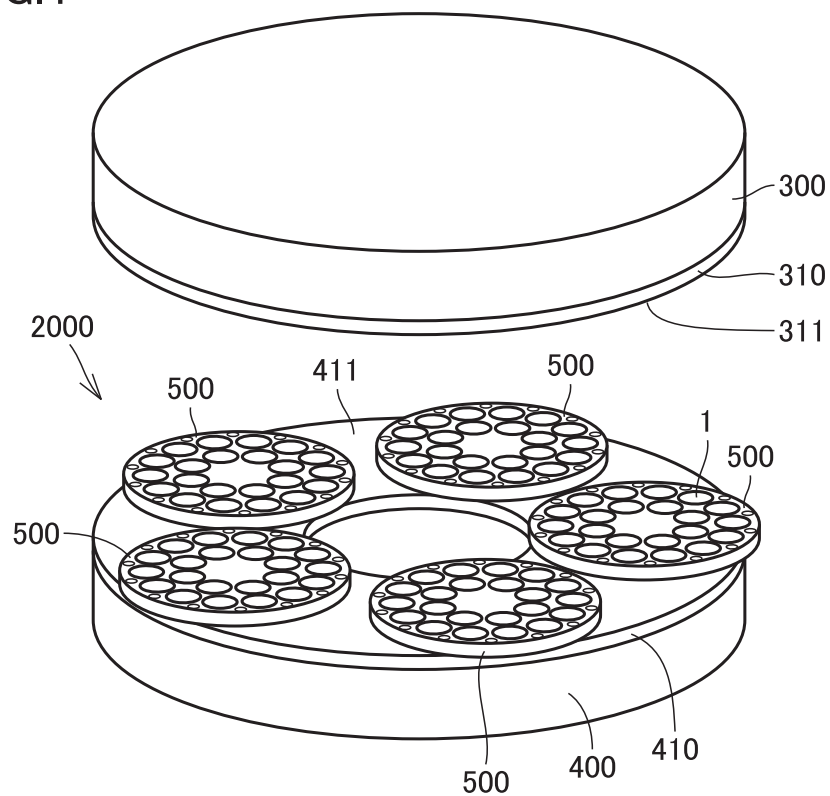


FIG.5

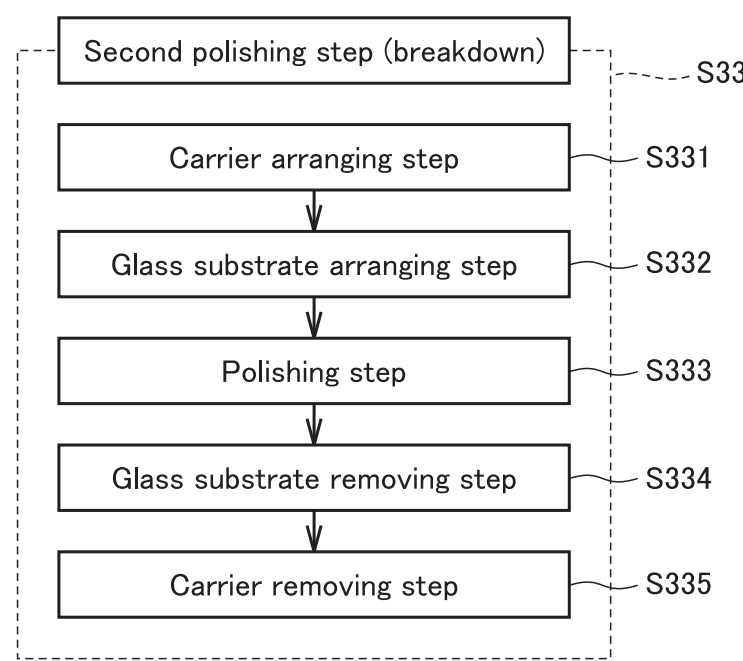


FIG.6

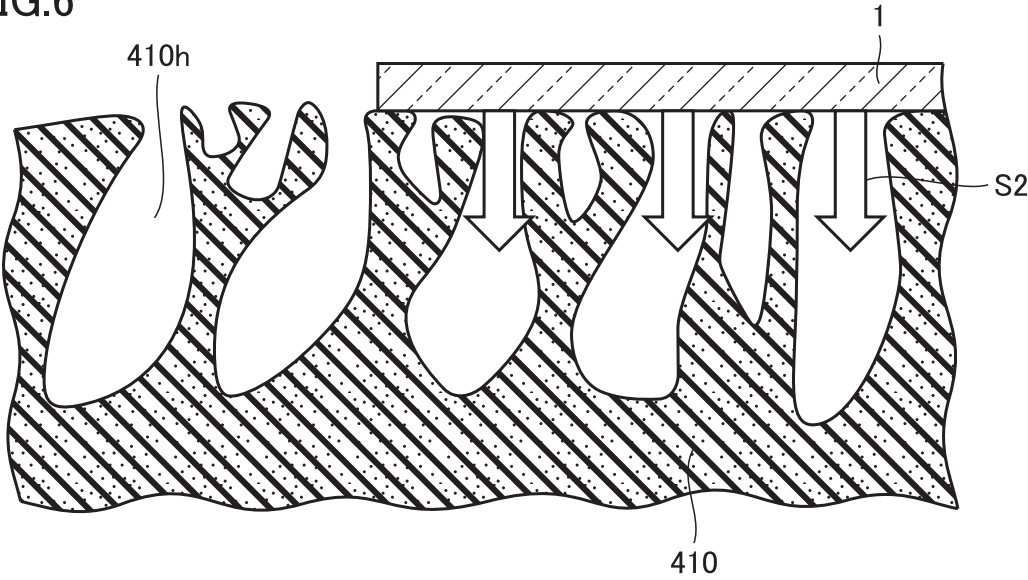


FIG.7

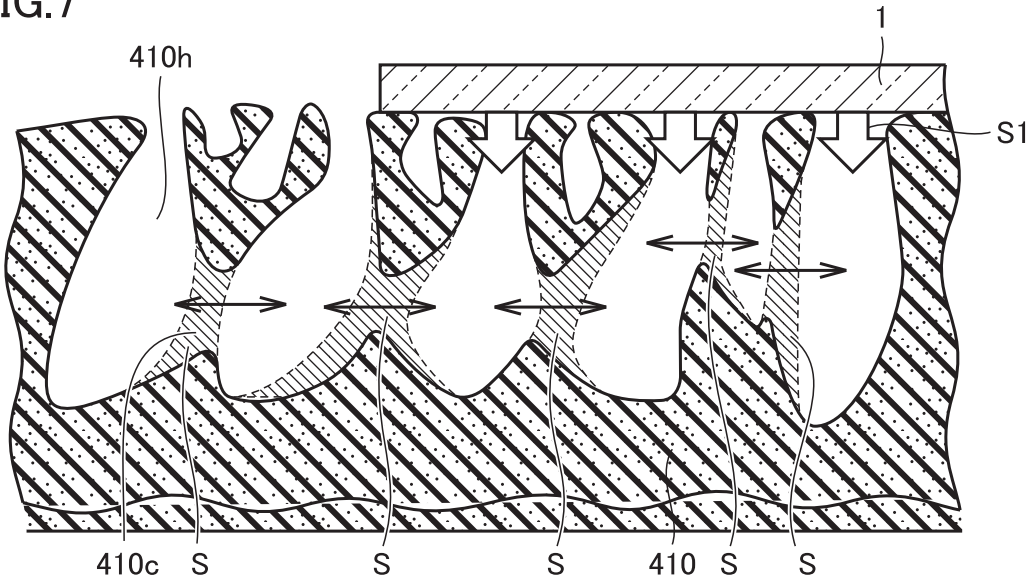


FIG.8

	Attraction force (g/cm ²)	Number of communication holes in polishing pad	Accumulation status of slurry on pad at the time of substrate removal	Concentration of slurry on pad at the time of substrate removal (wt%)	Defect inspection	Read-write test
Work. Ex. 1	15.0	35	Accumulated	15	B	B
Work. Ex. 2	14.5	35	Accumulated	20	B	B
Work. Ex. 3	13.0	35	Accumulated	25	A	A
Work. Ex. 4	14.0	63	Accumulated	15	B	B
Work. Ex. 5	13.0	88	Accumulated	15	A	A
Comp. Ex. 1	17.5	24	Not accumulated	0	D	D
Comp. Ex. 2	17.0	24	Accumulated	15	D	D
Comp. Ex. 3	16.0	35	Not accumulated	0	C	C